

**IN THE SPECIFICATION**

The paragraph beginning on page 10, fifth line from the bottom and ending on page 11, line 15 has been amended to read as follows:

61 --First, referring to Fig. 1A, bump electrodes 3 are formed by a known method on electrode pads 2 of an IC board 1 constituting a semiconductor device 4 to form electrical connecting points thereof. Then, an electrically conductive adhesive 7A comprising a thermoplastic resin having a low bonding strength is supplied to either the bump electrodes 3 or input/output terminal electrodes 6 of a circuit board 5 which is a substrate on which the semiconductor device 4 is to be mounted. In Fig. 1A, the electrically conductive adhesive 7A is supplied to the bump electrode 3 side. Further, an adhesive 8A composed of a thermosetting resin having a high bonding strength is supplied to either a region of the semiconductor device 4 which is not involved in electrical connection or a region of the circuit board 5 which is not involved in electrical connection (a rear surface of the semiconductor device 4 or a mounting surface of the circuit board 5). In Fig. 1A, the adhesive is supplied to the semiconductor device 4 side. As a supplying method, an adhesive 8A in a liquid state may be supplied by means of a dispenser or alternatively an adhesive 8A made into a film may be supplied by the transfer method or the like.--

**IN THE CLAIMS**

Please amend claims 1 and 7 to read as follows:

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1. A method of producing a mounting structure comprising:  
a connecting step of flip-chip mounting a semiconductor device onto a substrate;